TOSHIBA Rectifier Silicon Diffused Type

CMG07

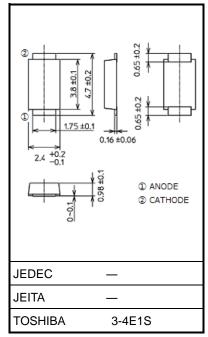
○ General-Purpose Rectifiers

- Repetitive peak reverse voltage : V_{RRM} = 400 V
- Average forward current : IF(AV) = 1 A
- Peak forward voltage : $V_{FM} = 1.1 V (max) @I_F = 1 A$
- Suitable for high-density board assembly due to the use of a small Toshiba Nickname: M-FLATTM

Absolute Maximum Ratings (Ta = 25°C)

| Characteristics | Symbol | Rating | Unit |
|---|------------------|------------|------|
| Repetitive peak reverse voltage | Vrrm | 400 | V |
| Average forward current | IF (AV) | 1 (Note1) | А |
| Non-repetitive peak forward surge current | IFSM | 30 (50 Hz) | А |
| Junction temperature | Тј | 150 | °C |
| Storage temperature | T _{stg} | -40 to 150 | °C |

Note1: Ta=78°C Device mounted on a ceramic board Board size : $50 \text{ mm} \times 50 \text{ mm}$ Soldering land size : $2 \text{ mm} \times 2 \text{ mm}$ Board thickness : 0.64 mmRectangular waveform : $\alpha = 180^{\circ}$



Weight: 0.023 g (typ.)

Note 2: Using continuously under heavy loads (e.g. the application

of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Electrical Characteristics (Ta = 25°C)

| Characteristics | Symbol | Test Condition | | Тур. | Max | Unit |
|---|-----------------------|---|---|------|-----|------|
| | VFM (1) | I _{FM} = 0.1 A (pulse test) | | 0.80 | — | |
| Peak forward voltage | VFM (2) | IFM = 0.7 A (pulse test) | - | 0.91 | _ | V |
| | VFM (3) | I _{FM} = 1 A (pulse test) | | 0.94 | 1.1 | |
| Peak repetitive reverse current | IRRM | V _{RRM} = 400 V (pulse test) | Ι | — | 10 | μΑ |
| Thermal resistance (junction to ambient) | | $\begin{array}{llllllllllllllllllllllllllllllllllll$ | _ | _ | 60 | |
| | Rth (j-a) | Device mounted on a glass-epoxy board board size 50 mm × 50 mm soldering land size 6 mm × 6 mm board thickness 1.6 mm | _ | _ | 125 | °C/W |
| | | $\begin{array}{ccc} \text{Device mounted on a glass-epoxy board} \\ \text{board size} & 50 \text{ mm} \times 50 \text{ mm} \\ \text{soldering land size} & 2.1 \text{ mm} \times 1.4 \text{ mm} \\ \text{board thickness} & 1.6 \text{ mm} \end{array}$ | _ | _ | 200 | |
| Thermal resistance (junction to lead) | R _{th (j-ℓ)} | _ | | _ | 16 | °C/W |

Start of commercial production 2008-10

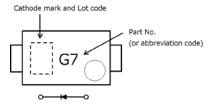
2018-07-06

Unit: mm

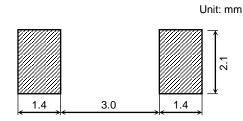
TOSHIBA

Marking

| Abbreviation Code | Part No. |
|-------------------|----------|
| G7 | CMG07 |



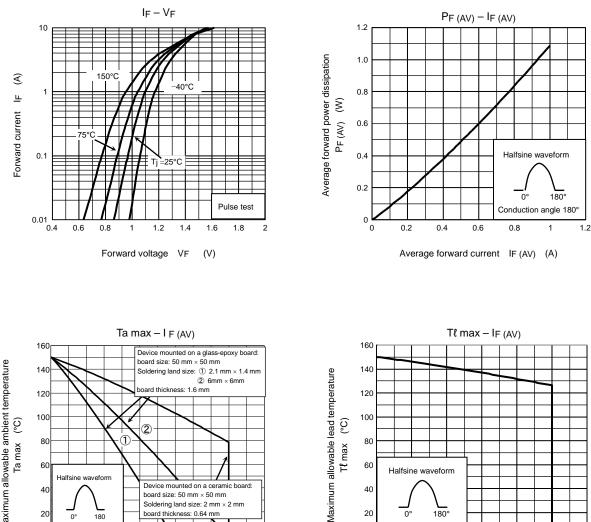
Land pattern dimensions for reference only

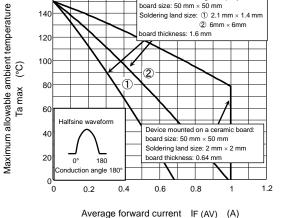


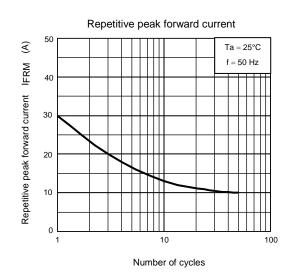
Handling Precaution

- The absolute maximum ratings are rated values that must not be exceeded during operation, even for aninstant. The following are the recommended general derating methods for designing a circuit board usingthis device.
 - VRRM : We recommend that the worst case voltage, including surge voltage, be no greater than 80% of the absolute maximum rating of VRRM for a DC circuit and be no greater than 50% of that of VRRM for an AC circuit. VRRM has a temperature coefficient of 0.1%/°C. Take this temperature coefficient into account designing a device at low temperature.
 - IF (AV) :We recommend that the worst case current be no greater than 80% of the absolute maximum rating of IF (AV) and Tj be below 120°C. When using this device, take the margin into consideration by using an allowable Ta max-IF (AV) curve.
 - IFSM :This rating specifies peak non-repetitive forward surge current. This only applies to an abnormal operation, which seldom occurs during the lifespan of a device.
 - Tj :Derate device parameters in proportion to this rating in order to ensure high reliability. We recommend that the junction temperature (Tj) of a device be kept below 120°C.
- 2) Thermal resistance (junction-to-ambient) varies with the mounting conditions of a device on a circuit board. An appropriate thermal resistance value should be used, considering the circuit board design and land pattern dimensions (provided for reference only).
- 3) For other design considerations, see the Toshiba website.

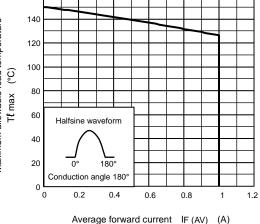
TOSHIBA







ľth (j-a) – t 1000 Device mounted on a glass-epoxy boar board size: 50 mm × 50 mm Soldering land size: 2.1 mm × 1.4 mm board thickness: 1.6 mm 1.6 100 rth (j-a) (°C/W) Device mounted on a glass-epoxy board size: 50 mm × 50 mm Soldering land size: 6 mm × 6 mm board thickness: 1.6 mm 10 size: 50 mm × 50 mm ing land: size 2 mm × 2 mm thickness: 0.64 mm 0.001 0.01 0.1 10 100 1000 1 Time t (s)



Transient thermal resistance

TOSHIBA

RESTRICTIONS ON PRODUCT USE

Toshiba Corporation and its subsidiaries and affiliates are collectively referred to as "TOSHIBA". Hardware, software and systems described in this document are collectively referred to as "Product".

- TOSHIBA reserves the right to make changes to the information in this document and related Product without notice.
- This document and any information herein may not be reproduced without prior written permission from TOSHIBA. Even with TOSHIBA's written permission, reproduction is permissible only if reproduction is without alteration/omission.
- Though TOSHIBA works continually to improve Product's quality and reliability, Product can malfunction or fail. Customers are responsible for complying with safety standards and for providing adequate designs and safeguards for their hardware, software and systems which minimize risk and avoid situations in which a malfunction or failure of Product could cause loss of human life, bodily injury or damage to property, including data loss or corruption. Before customers use the Product, create designs including the Product, or incorporate the Product into their own applications, customers must also refer to and comply with (a) the latest versions of all relevant TOSHIBA information, including without limitation, this document, the specifications, the data sheets and application notes for Product and the precautions and conditions set forth in the "TOSHIBA Semiconductor Reliability Handbook" and (b) the instructions for the application with which the Product will be used with or for. Customers are solely responsible for all aspects of their own product design or applications; (b) evaluating and determining the applicability of any information contained in this document, or in charts, diagrams, programs, algorithms, sample application circuits, or any other referenced documents; and (c) validating all operating parameters for such designs and applications. TOSHIBA ASSUMES NO LIABILITY FOR CUSTOMERS' PRODUCT DESIGN OR APPLICATIONS.
- PRODUCT IS NEITHER INTENDED NOR WARRANTED FOR USE IN EQUIPMENTS OR SYSTEMS THAT REQUIRE EXTRAORDINARILY HIGH LEVELS OF QUALITY AND/OR RELIABILITY, AND/OR A MALFUNCTION OR FAILURE OF WHICH MAY CAUSE LOSS OF HUMAN LIFE, BODILY INJURY, SERIOUS PROPERTY DAMAGE AND/OR SERIOUS PUBLIC IMPACT ("UNINTENDED USE"). Except for specific applications as expressly stated in this document, Unintended Use includes, without limitation, equipment used in nuclear facilities, equipment used in the aerospace industry, medical equipment, equipment used for automobiles, trains, ships and other transportation, traffic signaling equipment, equipment used to control combustions or explosions, safety devices, elevators and escalators, devices related to electric power, and equipment used in finance-related fields. IF YOU USE PRODUCT FOR UNINTENDED USE, TOSHIBA ASSUMES NO LIABILITY FOR PRODUCT. For details, please contact your TOSHIBA sales representative.
- Do not disassemble, analyze, reverse-engineer, alter, modify, translate or copy Product, whether in whole or in part.
- Product shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any
 applicable laws or regulations.
- The information contained herein is presented only as guidance for Product use. No responsibility is assumed by TOSHIBA for any infringement of patents or any other intellectual property rights of third parties that may result from the use of Product. No license to any intellectual property right is granted by this document, whether express or implied, by estoppel or otherwise.
- ABSENT A WRITTEN SIGNED AGREEMENT, EXCEPT AS PROVIDED IN THE RELEVANT TERMS AND CONDITIONS OF SALE FOR PRODUCT, AND TO THE MAXIMUM EXTENT ALLOWABLE BY LAW, TOSHIBA (1) ASSUMES NO LIABILITY WHATSOEVER, INCLUDING WITHOUT LIMITATION, INDIRECT, CONSEQUENTIAL, SPECIAL, OR INCIDENTAL DAMAGES OR LOSS, INCLUDING WITHOUT LIMITATION, LOSS OF PROFITS, LOSS OF OPPORTUNITIES, BUSINESS INTERRUPTION AND LOSS OF DATA, AND (2) DISCLAIMS ANY AND ALL EXPRESS OR IMPLIED WARRANTIES AND CONDITIONS RELATED TO SALE, USE OF PRODUCT, OR INFORMATION, INCLUDING WARRANTIES OR CONDITIONS OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, ACCURACY OF INFORMATION, OR NONINFRINGEMENT.
- Do not use or otherwise make available Product or related software or technology for any military purposes, including without limitation, for the design, development, use, stockpiling or manufacturing of nuclear, chemical, or biological weapons or missile technology products (mass destruction weapons). Product and related software and technology may be controlled under the applicable export laws and regulations including, without limitation, the Japanese Foreign Exchange and Foreign Trade Law and the U.S. Export Administration Regulations. Export and re-export of Product or related software or technology are strictly prohibited except in compliance with all applicable export laws and regulations.
- Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product. Please use Product in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. TOSHIBA ASSUMES NO LIABILITY FOR DAMAGES OR LOSSES OCCURRING AS A RESULT OF NONCOMPLIANCE WITH APPLICABLE LAWS AND REGULATIONS.

TOSHIBA ELECTRONIC DEVICES & STORAGE CORPORATION

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Rectifiers category:

Click to view products by Toshiba manufacturer:

Other Similar products are found below :

 70HFR40
 RL252-TP
 150KR30A
 1N5397
 NTE5841
 NTE6038
 SCF5000
 1N4002G
 1N4005-TR
 JANS1N6640US
 481235F

 RRE02VS6SGTR
 067907F
 MS306
 70HF40
 T85HFL60S02
 US2JFL-TP
 A1N5404G-G
 CRS04(T5L,TEMQ)
 ACGRA4007-HF

 ACGRB207-HF
 CLH03(TE16L,Q)
 ACGRC307-HF
 ACEFC304-HF
 NTE6356
 NTE6359
 NTE6002
 NTE6023
 NTE6077

 85HFR60
 40HFR60
 70HF120
 85HFR80
 D126A45C
 SCF7500
 D251N08B
 SCHJ22.5K
 SM100
 SCPA2
 SCH10000
 SDHD5K
 VS

 12FL100S10
 ACGRA4001-HF
 D1821SH45T
 PR
 D1251S45T
 NTE6358
 NTE6162
 NTE5850